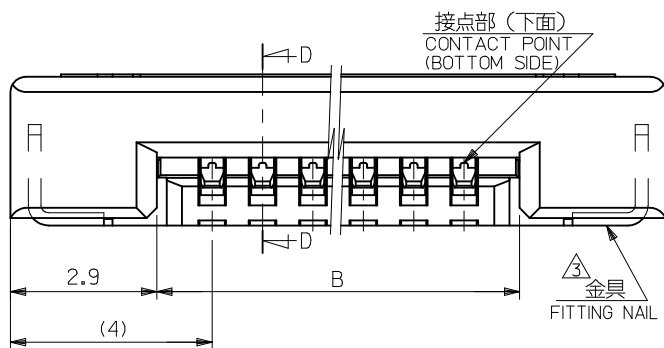
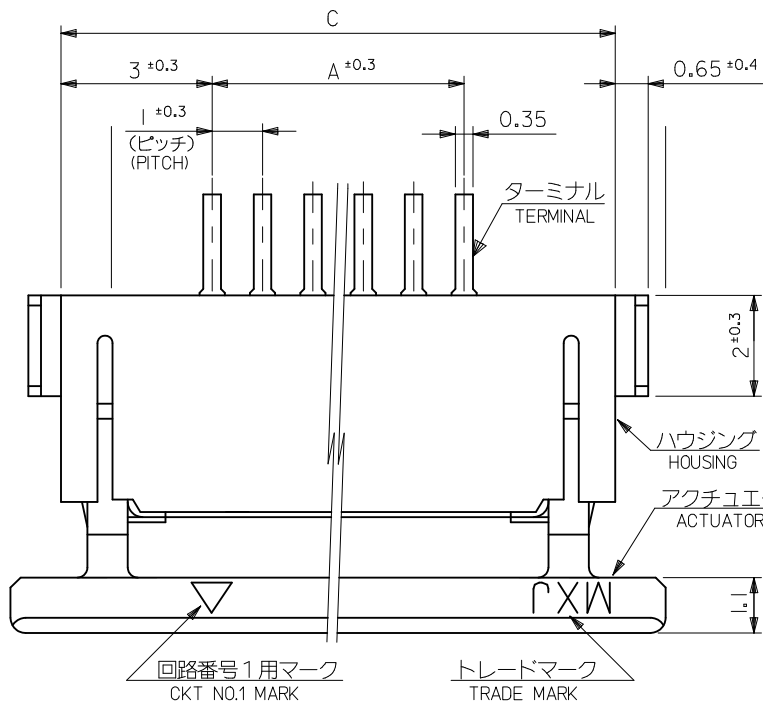
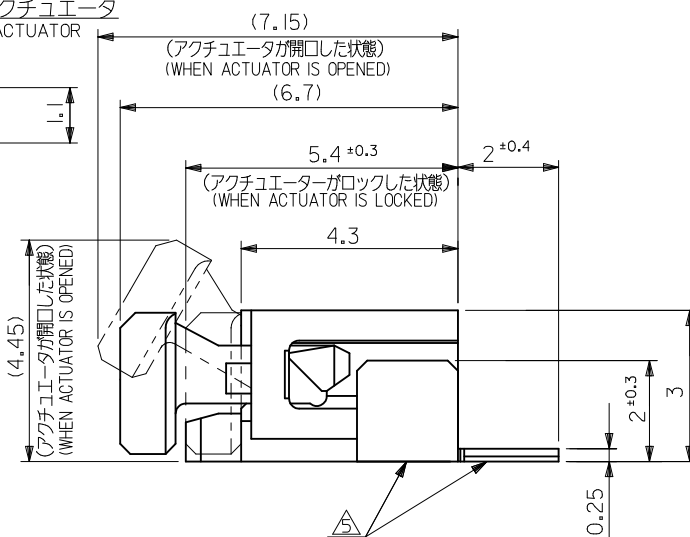
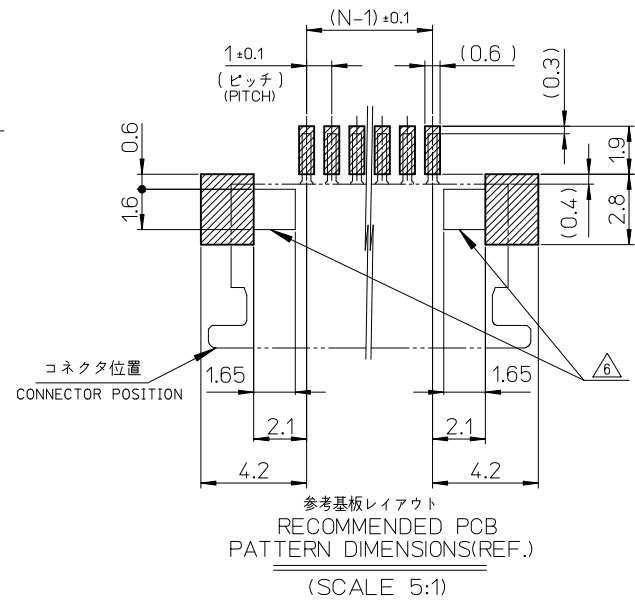
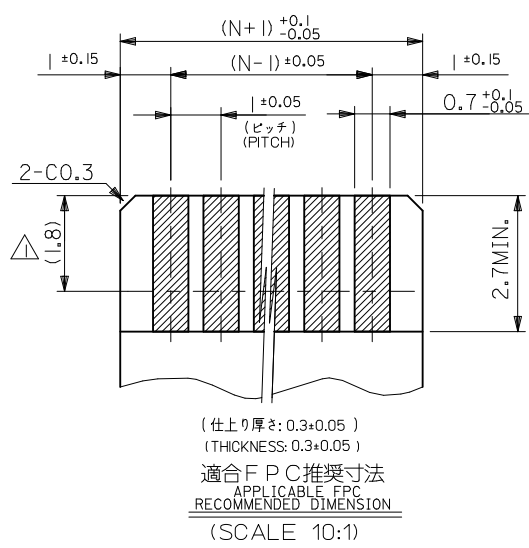


SECT.D-D



35	31.2	29	52271-3069	30
34	30.2	28	52271-2969	29
33	29.2	27	52271-2869	28
32	28.2	26	52271-2769	27
31	27.2	25	52271-2669	26
30	26.2	24	52271-2569	25
29	25.2	23	52271-2469	24
28	24.2	22	52271-2369	23
27	23.2	21	52271-2269	22
26	22.2	20	52271-2169	21
25	21.2	19	52271-2069	20
24	20.2	18	52271-1969	19
23	19.2	17	52271-1869	18
22	18.2	16	52271-1769	17
21	17.2	15	52271-1669	16
20	16.2	14	52271-1569	15
19	15.2	13	52271-1469	14
18	14.2	12	52271-1369	13
17	13.2	11	52271-1269	12
16	12.2	10	52271-1169	11
15	11.2	9	52271-1069	10
14	10.2	8	52271-0969	9
13	9.2	7	52271-0869	8
12	8.2	6	52271-0769	7
11	7.2	5	52271-0669	6
10	6.2	4	52271-0569	5
9	5.2	3	52271-0469	4
C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CIRCUITS
52271-**-29			CONNECTOR SERIES NO.	

REVISED EC NO: J2012-1390 DRWN:K.NAGUMO CHKD:K.TAKAHASHI APPR:K.MORI/KAWA	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY M.UMEDA	DATE 2005/03/08	TITLE 1.0 FPC CONN ZIF SMT (BOTTOM CONTACT) -LEAD FREE- molex				
		10 OVER 30 UNDER	± 0.25	CHECKED BY K.TOYODA	DATE 2005/03/08					
		30 OVER	± 0.3	APPROVED BY N.UKITA	DATE 2005/03/08					
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-52271-038		1 OF 2			
	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								



注記 NOTES

- △ 接点部までの嵌合長さ。
LENGTH TO CONTACT POINT.
2. 使用材料 MATERIAL
- ハウジング : 46 NYLON, UL94V-0
HOUSING
- アクチュエータ : PPS, UL94V-0
ACTUATOR
- ターミナル : リン青銅 (t=0.25)
TERMINAL PHOSPHOR BRONZE (t=0.25)
- メッキ : 接点部 : 金メッキ : 0.1 MICROMETER MIN.
CONTACT PORTION : GOLD PLATING : 0.1 MICROMETER MIN.
半田付部 : 錫メッキ : 1.0 MICROMETER MIN.
SOLDERING PORTION : TIN PLATING : 1.0 MICROMETER MIN.
下地 : ニッケルメッキ : 1.0 MICROMETER MIN.
UNDER PLATING : NICKEL PLATING : 1.0 MICROMETER MIN.
- 金具 : 銅合金 (t=0.25)
FITTING NAIL CAPPER ALLOY (t=0.25)
- メッキ : 錫メッキ : 1.0 MICROMETER MIN.
PLATING : TIN PLATING : 1.0 MICROMETER MIN.
下地 : ニッケルメッキ : 1.0 MICROMETER MIN.
UNDER PLATING : NICKEL PLATING : 1.0 MICROMETER MIN.
- △ 3. パターンはくり止め用金具
FITTING NAIL FOR PREVENTION OF PEELING
OF P.C.B. PATTERN.
4. エンボステープ梱包時は、アクチュエータがロックした状態とする。
IN THE PACKAGE, ACTUATOR OF PART NO.54550-***29 SHOULD BE LOCKED.
- △ 5. テール及び金具の平坦度は、0.15 以下とする。
TAIL AND NAIL COPLANARITY TO BE 0.15 MAXIMUM.
- △ 6. パターン書き込み禁止エリア
NO FOOT PRINT AREA.

FPC について :

- 打抜き方向は、導体側から補強板側を推奨致します。
- 補強フィルム材質は、ポリイミドを推奨致します。
- 接着剤は、熱硬化接着剤を推奨致します。

ABOUT FPC :

- RECOMMENDED PUNCHER DIRECTION :
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE
- RECOMMENDED MATERIAL :
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING BONDING AGENT

REVISED EC NO: J2012-1390 DRAWN:KAGUMO 2012/05/10 CHKD:K.TAKAHASHI 2012/05/10 APPR:K.MORI/KAWA 2012/05/17	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE		
				MM ONLY		---	METRIC	PROJECTION		
		10 UNDER	± 0.2	DRAWN BY M.UMEDA	DATE 2005/03/08	TITLE 1.0 FPC CONN ZIF SMT (BOTTOM CONTACT) -LEAD FREE-				
		10 OVER 30 UNDER	± 0.25	CHECKED BY K.TOYODA	DATE 2005/03/08					
		30 OVER	± 0.3	APPROVED BY N.UKITA	DATE 2005/03/08	molex				
	ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.					
REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE SHEET 1		SD-52271-038		2 OF 2				
		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							